

4

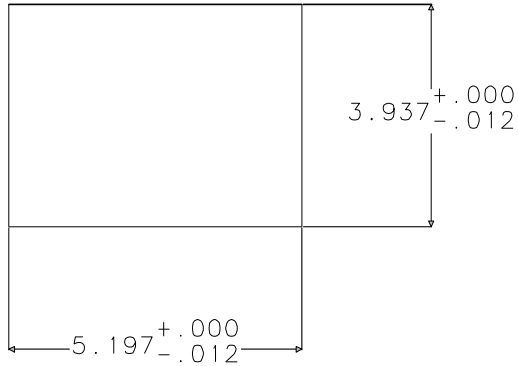
3

Dwg. NO. 2711

SH

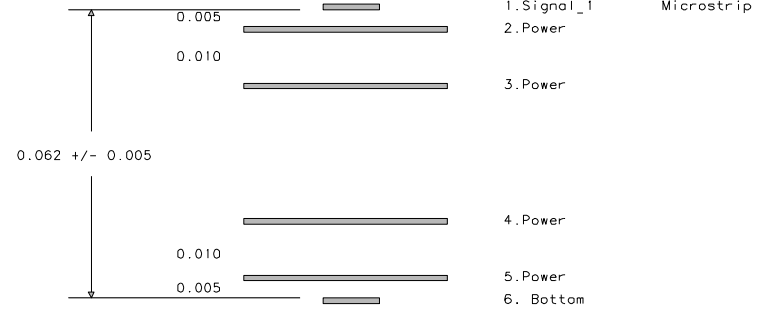
REV B

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Top - Comp.Side

Layer Order



Board Characteristics - 6 LAYER BOARD

0. All dimensions are given in inches unless specified otherwise.
1. Material FR4
2. Minimum trace width and clearance: 0.006"
4. 1 oz copper for all layers.
5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
6. Apply Solder Mask over bare copper.
8. Silkscreen on Component and Solder Sides.
10. FHS tolerances: +/- 0.003 unless specified otherwise.
11. Interlayer spacing as specified

BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.014	591	YES	---	
⊞	.032	20	YES	---	
⊕	.035	8	YES	---	
⊞	.041	52	YES	---	
⊖	.042	20	YES	---	
⊞	.057	8	YES	---	
⊕	.094	1	NO	---	
□	.098425197	2	YES	---	
	.104	2	YES	---	
	.106	8	NO	---	
	.15	3	NO	---	
	.2	2	YES	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX XXX DO NOT SCALE DRAWING		CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP			
		APPROVALS		DATE		TITLE	
TREATMENT		DRAWN M. Bogdan		2/18/2011		ASIC Tester Board Specification Drawing	
FINISH		CHECKED M. Bogdan		2/18/2011		SIZE FSCN NO.	
SIMILAR TO		ISSUED				Dwg. NO. 2711	
ACT. WT		CALC WT				REL B	
				SCALE 1/2		SHEET	

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